

isc N-Channel MOSFET Transistor

2SK1466

DESCRIPTION

- Drain Current $-I_D=16A@ T_C=25^\circ C$
- Drain Source Voltage-
: $V_{DSS}=900$ (Min)
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

APPLICATIONS

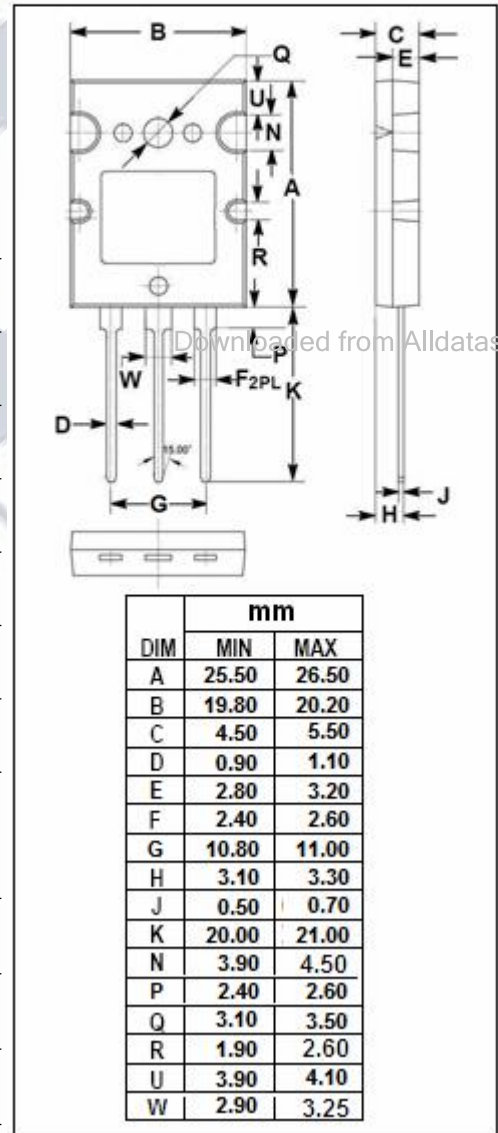
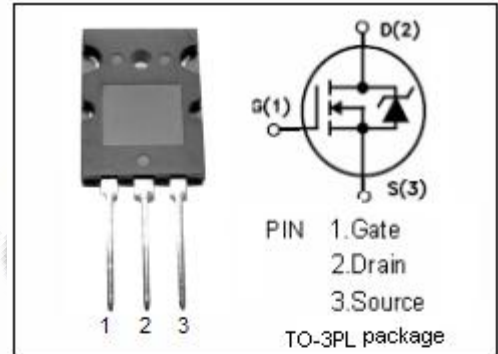
- Designed for high voltage, high speed power switching

ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ C$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage ($V_{GS}=0$)	900	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Drain Current-continuous@ $T_C=25^\circ C$	16	A
P_{tot}	Total Dissipation@ $T_C=25^\circ C$	250	W
T_j	Max. Operating Junction Temperature	150	$^\circ C$
T_{stg}	Storage Temperature Range	-55~150	$^\circ C$

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th j-c}$	Thermal Resistance, Junction to Case	1.25	$^\circ C/W$
$R_{th j-a}$	Thermal Resistance, Junction to Ambient	35.0	$^\circ C/W$



isc N-Channel Mosfet Transistor**2SK1466****• ELECTRICAL CHARACTERISTICS (T_c=25°C)**

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0; I _D = 10mA	900			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =10V; I _D =1mA	2.0		3.0	V
R _{DS(on)}	Drain-Source On-stage Resistance	V _{GS} =10V; I _D =8A		0.6	0.8	Ω
I _{GSS}	Gate Source Leakage Current	V _{GS} = ±30V; V _{DS} = 0			± 100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =900V; V _{GS} = 0			1	mA
V _{SD}	Diode Forward Voltage	I _F =16A; V _{GS} =0			1.8	V
t _r	Rise time			120		ns
t _{on}	Turn-on time	V _{GS} =10V; I _D =8A; R _L =50 Ω		155		ns
t _f	Fall time			200		ns
t _{off}	Turn-off time			1050		ns